

SPB106-WiFi 802.11b+g SMD WiFi Board

Data Sheet

SPB106

WiFi SMD Board



Revision History

Revision	Revision date	Description
PA1	2010-02-11	First issue
PA2	2010-02-17	Updated after review
A	2010-02-22	Release after review and updates
PB1	2010-02-26	Info about SDIO interface added.
B	2010-03-17	FCC number corrected
PC1	2010-04-12	RF test switch information added
PC2	2010-04-26	SPIO SPI interface updated. Solder profile updated
PC3	2010-06-18	Table and figure numbering corrected

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1 INTRODUCTION

1.1 Overview

SPB106 is SMD module with the HDG104 WLAN System In Package, SIP module and all peripheral components required. It is a complete solution designed to be surface mount on any host system needing a complete WiFi solution.

SPB106 enables a cost efficient ultra low power, high performance and feature rich client solution. It provides up to 54 Mbit/s data rate when operating in the OFDM mode and up to 11 Mbit/s data rate when operating in the DSSS/CCK mode.

The host interface supports SPI communication when used in the 10-pin RF-header connection (WLESS) and SDIO when used in a custom board with the AVR32UC3A3, and software drivers and a complete application example is included in Atmel AVR32 UC3B Software Framework from release 1.5.0 and onwards

1.2 Key Features

- Data Rates: 1, 2, 5.5, 6, 9, 11, 12, 18, 24, 36, 48, and 54Mbps
- Modulation: QPSK, 16QAM, 64QAM DBPSK, DQPSK, CCK, OFDM with BPSK
- WEP and AES hardware encryption accelerator up to 128 bits
- Chip Antenna and connector for external antenna (optional) mounted on the board.
- Low power consumption due to efficient class AB PA design
- UMA Compliant
- Advanced power management for optimum power consumption at varying load.
- Bluetooth Coexistence support
- Power Supply 3.3 V from EVK board
- Small footprint 25.8 X 20.6 mm
- RoHS Compliant

2 HARDWARE ARCHITECTURE

2.1 Block Diagram

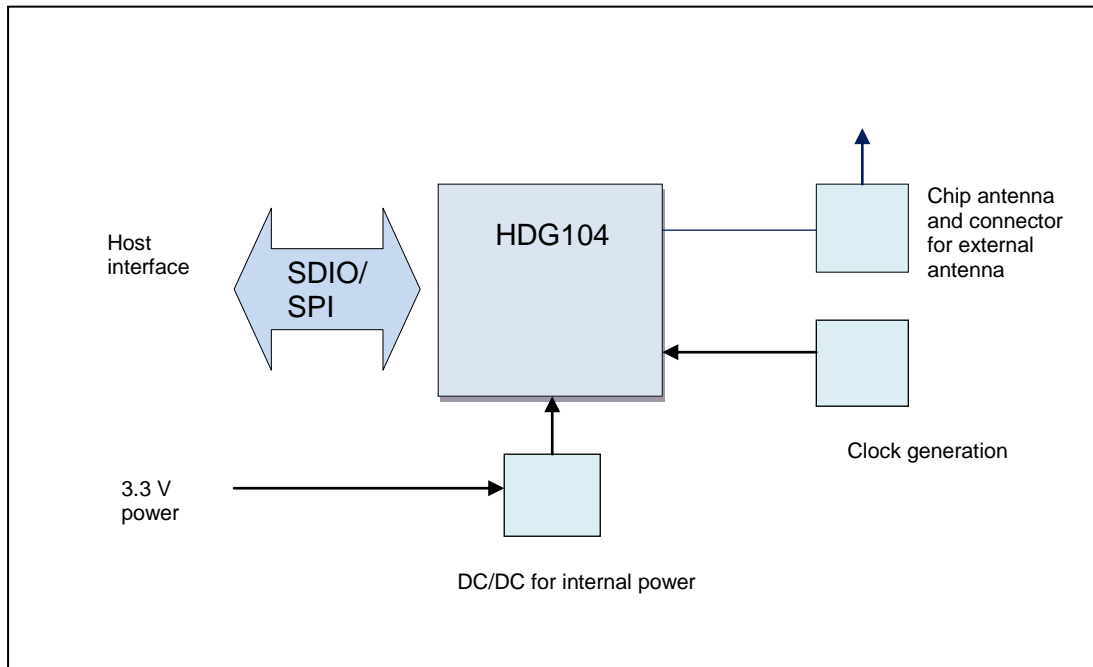


Figure 2.1: Block diagram.

2.2 Order information

Part No.	option	Batch size	Shipment package
SPB106/1		10/100	Unit in ESD bag
SPB106/3		1K/10K/50K	Tray
SPB106/e/3	Ext antenna connector not mounted.	1K/10K/50K	Tray

Table 2-1: Order information.

3 ELECTRICAL DATA

3.1 Absolute maximum ratings

Rating	Min	Max	Unit
Supply voltage	0	4	V
Input RF level		10	dBm
Storage temperature	-50	+125	°C

Table 3-1: Absolute maximum ratings. Exceeding any of the maximum ratings, even briefly lead to deterioration in performance or even destruction. Values indicates condition applied one at the time.

3.2 ESD

HDG104 withstands ESD voltages up to 2000 V tested with HBM (Human Body Model) according to JESD22-A114 and up to 300 V tested with MM (Machine Model) according to JESD22-A115.

3.3 Recommended operating conditions

Rating	Min	Typ	Max	Unit
Supply Voltage VCC	2.75	3.3	3.6	V
Operating temperature	-20	+25	+70	°C
Operating temperature, reduced spec, no damage.	-30	+25	+85	°C

Table 3-2: Recommended operating conditions

3.4 Power Consumption

3.4.1 Current Consumption

Mode	Conditions	Parameter	Voltage	Min	Typ	Max	Unit
All modes		VBAT_P+VCC+VPA+VBAT_32K	3.6 V			250	mA
All modes		VPA	3.6 V			150	mA
All modes		VBAT_P+VCC	3.6 V			150	mA
All modes		DVDD	1.2 V			100	mA
All modes	25°C	VBAT_32K	3.3 V		10		µA
Tx	25°C	DVDD	1.2 V		15		mA

Rx	25°C	DVDD	1.2 V		60		mA
Sleep	25°C	VBAT_P+VCC+ VPA+VBAT_32K	3.3 V		30		µA
Sleep	25°C	DVDD	1.2 V		110		µA
Soft Shutdown	25°C	VBAT_P+VCC+ VPA+VBAT_32K	3.3 V		20		µA
Soft Shutdown	25°C	DVDD	1.2V		70		µA
Shutdown,	25°C DVDD OFF	VBAT_P+VCC+ VPA+VBAT_32K	3.3 V		15		µA

Table 3-3: Current consumption in different modes.

3.4.2 Power Consumption

T_{amb}=25°C, VCC=VBAT_P=VBAT_32K=VPA=3.3 V, DVDD =1.2 V

Mode	OutputPower	Power Consumption	Comments
TX 802.11b	+17 dBm	725 mW	1, 2, 5.5, 11 Mbit/s
TX 802.11g	+14 dBm	590mW	6, 9, 12, 18, 24, 36, 48, 54 Mbit/s
RX 802.11b	N/A	220mW	
RX 802.11g	N/A	230mW	
Power Save	N/A	0,4 mW	Receive only, 2s RX beacons
Sleep	N/A	0,2mW	No receive, FW loaded, only LFC running
Soft Shutdown	N/A	0,15 mW	No receive, No FW loaded, only LFC running
Shutdown	N/A	0,05 mW	No FW loaded, DVDD OFF,

Table 3-4: Current consumption in different modes.

3.5 RF Performance

VCC=VPA= 2.75 – 3.6V, DVDD=1.15 - 1.25V External supply, T_{amb}= -20 – +70°C

Parameter	Conditions	Min	Typical	Max	Units
Frequency range		2400		2500	MHz
RF impedance			50		ohm
Transmitter performance					
Output power	QPSK, Calibrated.	+16,5	+17	+17,5	dBm
Output power	OFDM 54Mbit/s, Calibrated.	+13,5	+14	+14,5	dBm
EVM at +15dBm	QPSK		30	35	%
EVM at +11dBm	OFDM 54MBit/s		3.5	5	%

Receiver performance				
Receiver sensitivity	DPSK 1Mbit/s		-96	dBm
Receiver sensitivity	QDPSK 2Mbit/s		-92	dBm
Receiver sensitivity	CCK/DPSK 5.5Mbit/s		-91	dBm
Receiver sensitivity	CCK/BPSKK 11Mbit/s		-88	dBm
Receiver sensitivity	OFDM 6Mbit/s		-91	dBm
Receiver sensitivity	OFDM 9Mbit/s		-90	dBm
Receiver sensitivity	OFDM 12Mbit/s		-88	dBm
Receiver sensitivity	OFDM 18Mbit/s		-86	dBm
Receiver sensitivity	OFDM 24Mbit/s		-83	dBm
Receiver sensitivity	OFDM 36Mbit/s		-80	dBm
Receiver sensitivity	OFDM 48Mbit/s		-76	dBm
Receiver sensitivity	OFDM 54Mbit/s		-74	dBm

Table 3-5: RF performance.

3.6 Digital pin characteristics

3.6.1 SDIO timing characteristics

The SDIO/SPI-interface can run in two different modes, Default mode and High speed mode. SDIO 1-bit default mode is selected at Power On Reset. The default mode is shown in Figure 3-1: SDIO/SPI timing diagram (default mode) and table: Table 3-6: SDIO/SPI timing parameter values (default mode). For the high speed mode see Figure 3-2: SDIO/SPI timing diagram (high speed mode) and Table 3-7: SDIO/SPI timing parameter values (high speed mode).
 Condition:
 VDDIO= 1.7 – 3.6 V, TA= -20 – +70°C

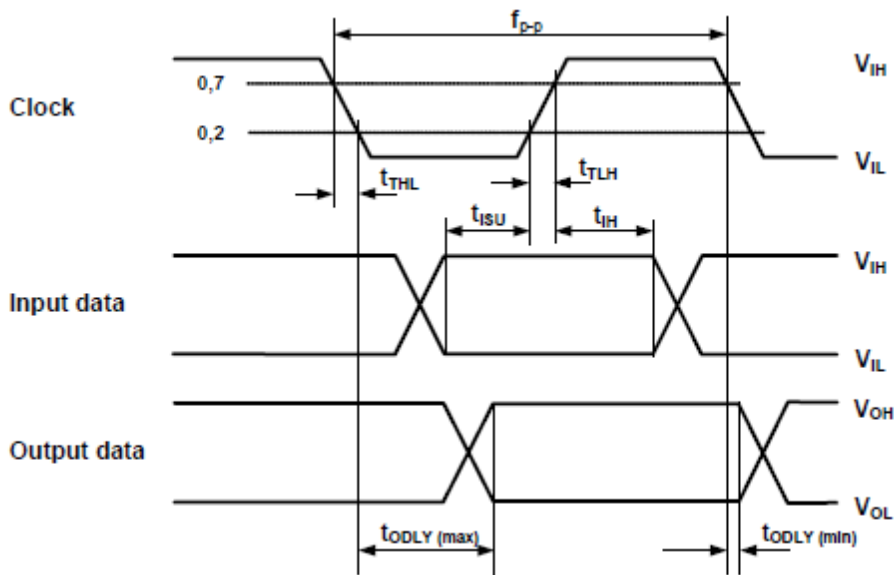


Figure 3-1: SDIO/SPI timing diagram (default mode)

Parameter	Symbol	Min	Max	ns	Comments
Input set-up time	t _{ISU}	5		ns	
Input hold time	t _{IH}	5		ns	
Clock fall time	t _{THL}		10	ns	
Clock rise time	t _{T LH}		10	ns	
Output delay time	t _{ODLY}	0	40	ns	

Table 3-6: SDIO/SPI timing parameter values (default mode)

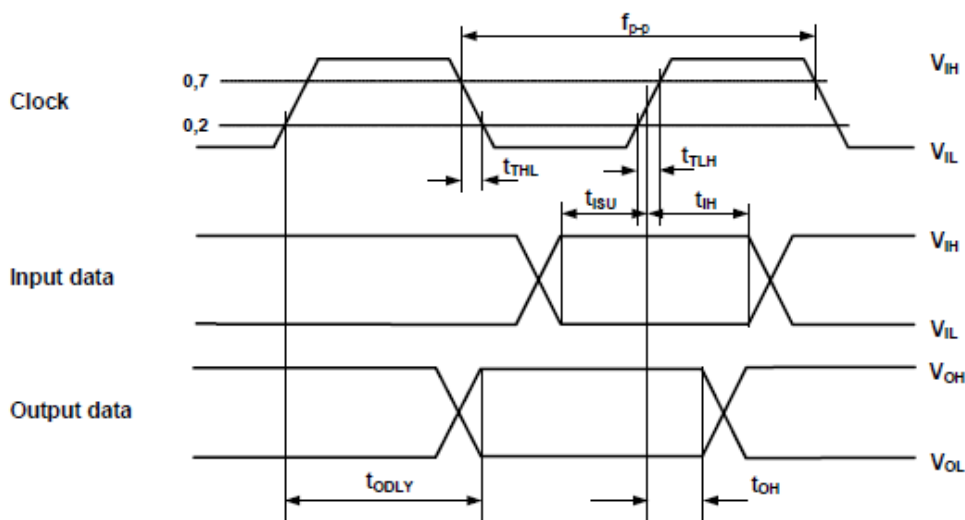


Figure 3-2: SDIO/SPI timing diagram (high speed mode)

Parameter	Symbol	Min	Max	ns	Comments
Clock fall time	t _{THL}		3	ns	
Clock rise time	t _{T LH}		3	ns	
Output delay time	t _{ODLY}	2,5	14	ns	
Output hold time	t _{OH}	2.5		ns	

Table 3-7: SDIO/SPI timing parameter values (high speed mode)

4 PIN CONFIGURATIONS

4.1 Pin Configuration

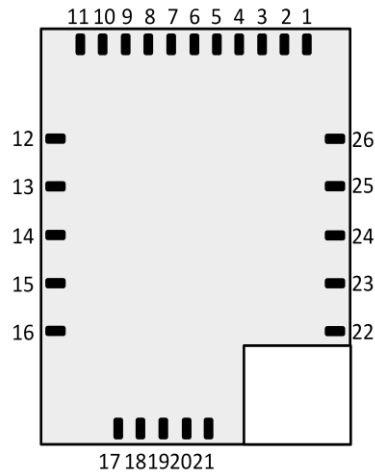


Figure 4.1: Package pin out, top view

4.2 Pin assignments

Pin	Function	Type	Description
1	SDIO_D2	I/O	Databit 2
2	NC	-	Not used
3	SDIO_D1 / SPI_IRQ	I/O	Databit 1 / Interrupt
4	RESET	I	Shutdown
5	SDIO_D3 / SPI_CS	I/O	Databit 3/ SPI Chip Select
6	SDIO_CMD / SPI_MOSI	I/O	SDIO_CMD / SPI_MOSI
7	SDIO_D0 / SPI_MISO	I/O	Databit 0 / SPI_MISO
8	SD_CLK / SPI_CLK	I	SPI Clock
9	GND	S	Ground
10	VCC	S	Power supply, 3.3V
11-23	GND	S	Ground
24	DVDD	S	Power supply to HDG104 (for version without on-board DC-DC converter)
25	GND	S	Ground
26	GND	S	Ground

Table 4-1: Pin assignments

5 APPLICATION INFORMATION

5.1 Power Supply

SPB106 should be powered by a 3.3V supply.

5.2 Reset/Shutdown

The RESET pin is connected to HDG104 SHUTDOWN pin, and is active low. It should be set high in normal operation.

Since it has an internal pull-up, it can be left unconnected. Pulling the SHUTDOWN pin low, set the SPB106 in Shutdown mode. This turns OFF most parts of the circuit and minimizes the current consumption. All I/O interface pins are set to predefined states (high, low or high-z) when in Shutdown mode. To end Shutdown mode set SHUTDOWN pin high and reload FW and MIB.

5.3 Power save

Power save is a energy saving mode where SPB106 is only listening at regular intervals for the beacons transmitted from an access point and is set in sleep mode in between. During this sleep mode, FW is kept in RAM but all not needed functions are turned off. Since the receive time is very short compared to the listening interval the average current consumption is reduced significantly. The timing of the listening interval is based on the LFC (32 kHz) clock. The LFC is implemented internally.

For detailed information regarding the power save function see the Application manual.

5.4 Interfaces

To communicate with the SPB106 the SPI or SDIO interface is used.

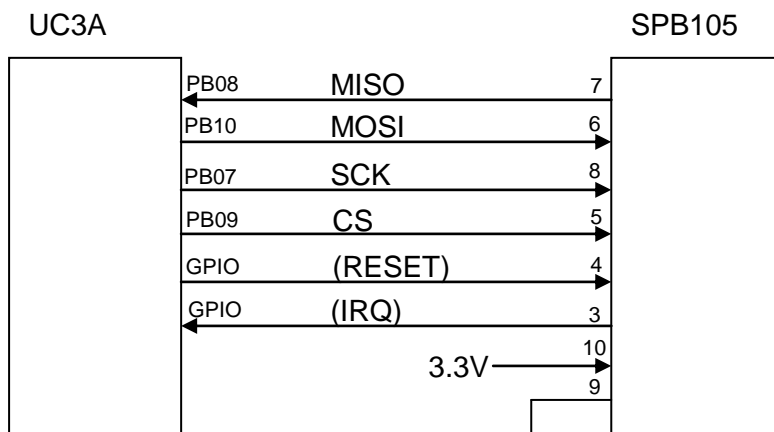
5.4.1 SPI interface

The SPI interface signals are connected to the host boards SPI bus. It can coexist with other SPI devices on the same bus. The SPI_CS signal is the Chip Select signal, and it is implemented with a General Purpose I/O pin.

The SPI bus signals on the Atmel AVR32 family processors use different pins for different parts in the family, and depending on the application the processors can be configured to use different pins for SPI. As an example for the UC3A the following configuration can be made:

Pin	Function	Pin on AVR32	Description
1	-	-	Not used
2	-	-	Not used
3	SPI_IRQ	Any GPIO pin, configured to generate interrupt. (optional)	Interrupt
4	RESET	Any GPIO pin, put SPB106 in shutdown mode, reset. (optional)	Shutdown

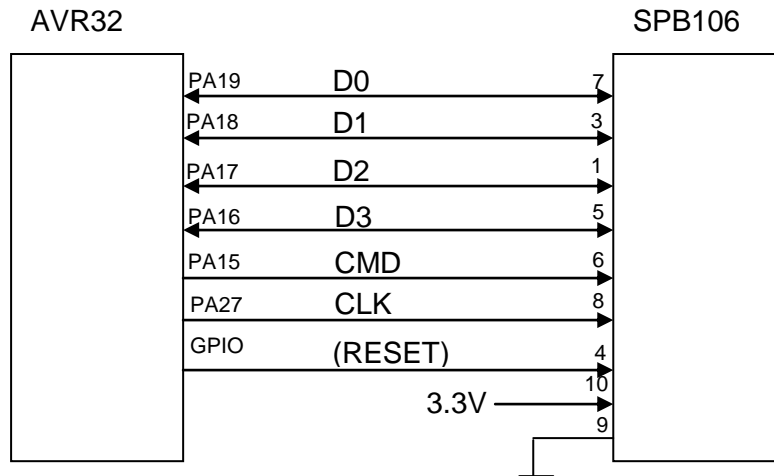
5	SPI_CS	PB09 (SPI1_NPCS[0])	SPI Chip Select
6	SPI_MOSI	PB10 (SPI1 MOSI)	SPI_MOSI
7	SPI_MISO	PB08 (SPI1 MISO)	SPI_MISO
8	SPI_CLK	PB07 (SPI1 SCK)	SPI Clock
9, 11-23, 25,26	GND	-	Ground
10	VCC	-	Power supply, 3.3V
24	DVDD	-	Power supply 1.2V (for version without on-board DC-DC converter)



5.4.2 SDIO interface

For the SDIO interface four GPIO pins are used as data bits, these can be any of the MCI groups available on the AVR32 processor. The SDIO_CMD should be in the same group. The optional RESET can be connected to be any GPIO pin. This is an example of pins to can be used:

Pin	Function	Pins on AVR32 family processor	Description
1	SDIO_D2	PA17 (MCI – DATA10)	Databit 2
2	-	-	Not used
3	SDIO_D1	PA18 (MCI – DATA9)	Databit 1
4	RESET	Any GPIO (optional)	Shutdown
5	SDIO_D3	PA16 (MCI – DATA11)	Databit 3
6	SDIO_CMD	PA15 (MCI – CMD [1])	SDIO_CMD
7	SDIO_D0	PA19 (MCI – DATA8)	Databit 0
8	SD_CLK	PA27 (MCI – CLK)	SDIO Clock
9, 11-23, 25,26	GND	-	Ground
10	VCC	-	Power supply 3.3V
24	DVDD	-	Power supply 1.2V (for version without on-board DC-DC converter)



5.5 RF interface

The SPB106 has a high performance chip antenna as the primary RF interface. To enable RF measurements a coaxial connector is available. The connector is switching and compatible with MuRata measurement probe MXHS83QH3000 and similar.

5.6 General application information

5.6.1 Design directions

The design using the SPB106 must be performed according to good RF design considerations. All the leads shall be as short as possible between the circuit pins and the external components. Keep the area under the antenna free from all metal including signal or ground wires.

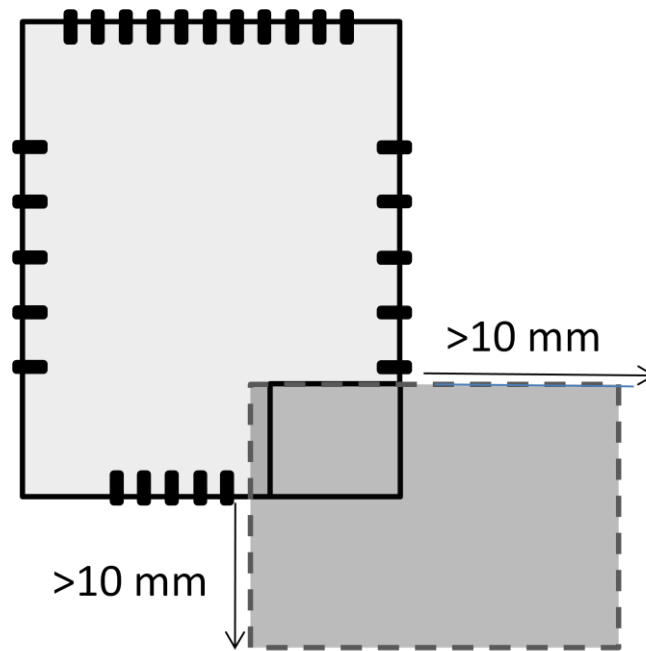


Figure 5-1: Proposed keep out area

5.6.2 Soldering

The SPB106 is a surface mount PCB module. The recommended reflow soldering profile is pictured in Figure 5-2.

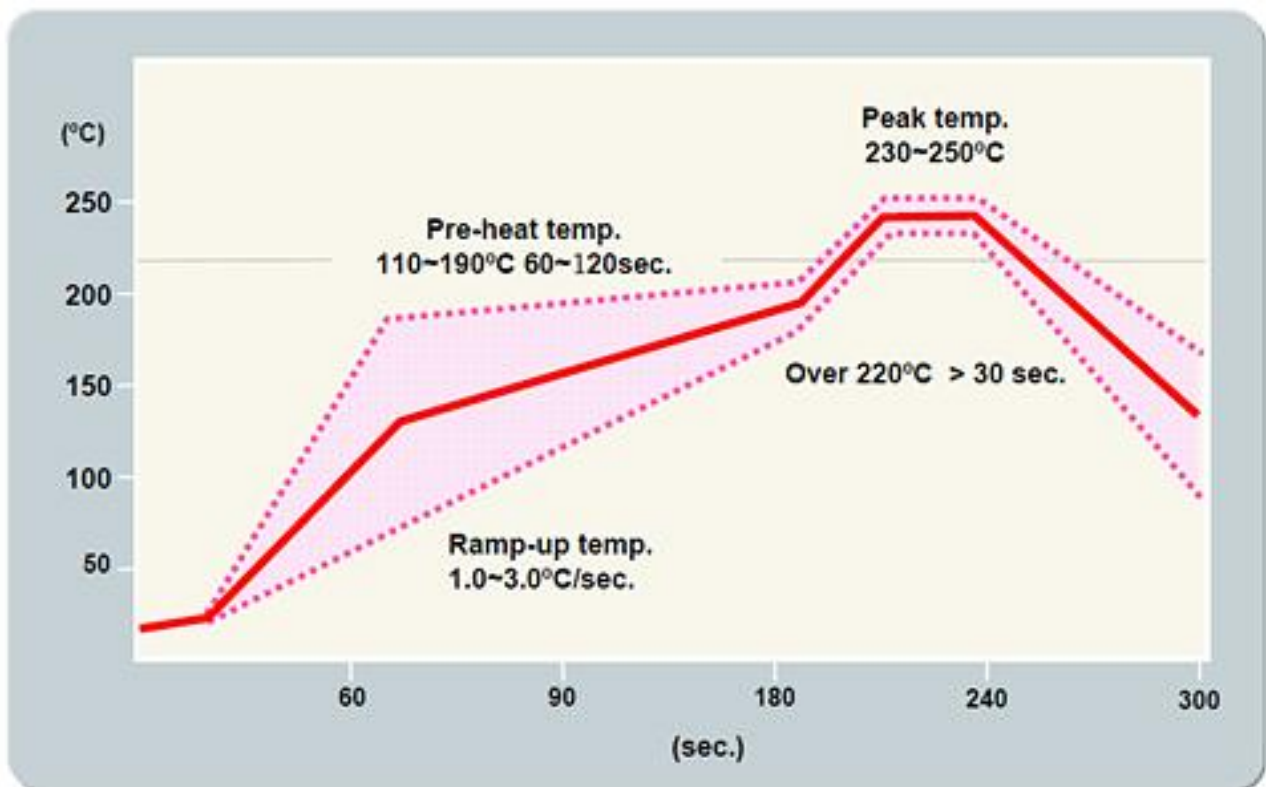


Figure 5-2: Reflow Temperature Profile.

Type	Rising Zone	Preheat Zone	Reflow Zone	Peak Zone	Cooldown Zone	Comment
PSR	125°C-Peak 1-3 °C/s	110- 190°C 60-120 s	>220°C >30s	230- 250°C	Peak-125°C No	

Table 5-1: Zone temperatures

5.6.3 Environmental statement

The SPB106 is designed and manufactured to comply with the RoHS and Green directives.

6 PACKAGE SPECIFICATIONS

6.1 Mechanical outline of the SPB106 circuit board

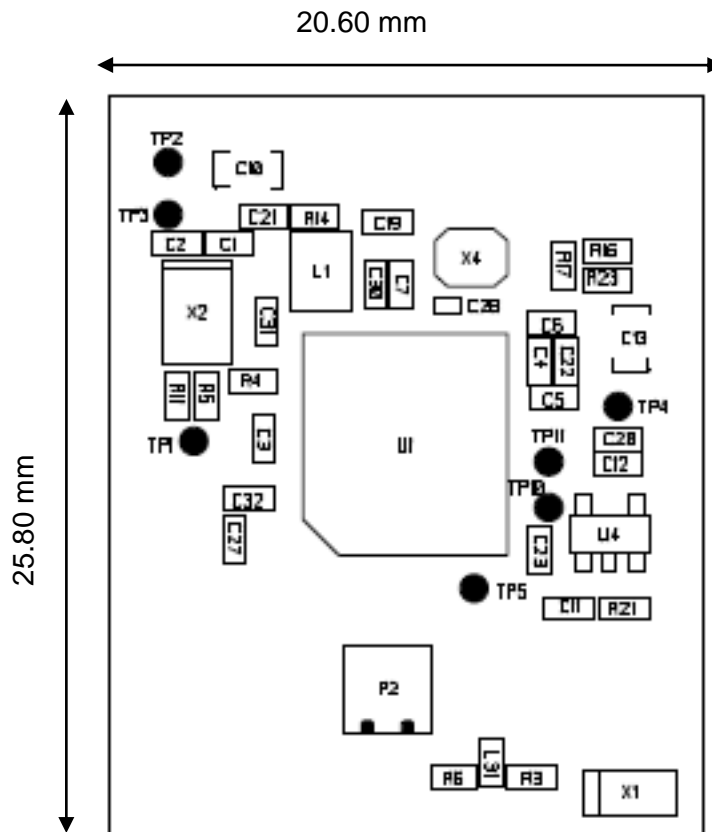
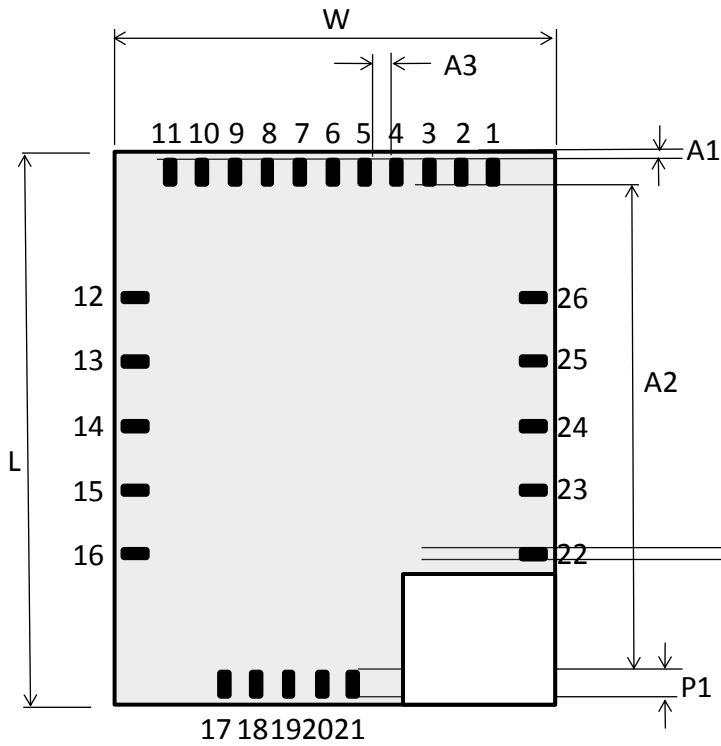


Figure 6-1: Mechanical drawing (top view)

6.2 Markings on the SPB106

The circuit board are marked with a sticker with the units serial number. The FCC id. X02SHDG104 is printed on the top of the PCB.

6.3 Package dimensions

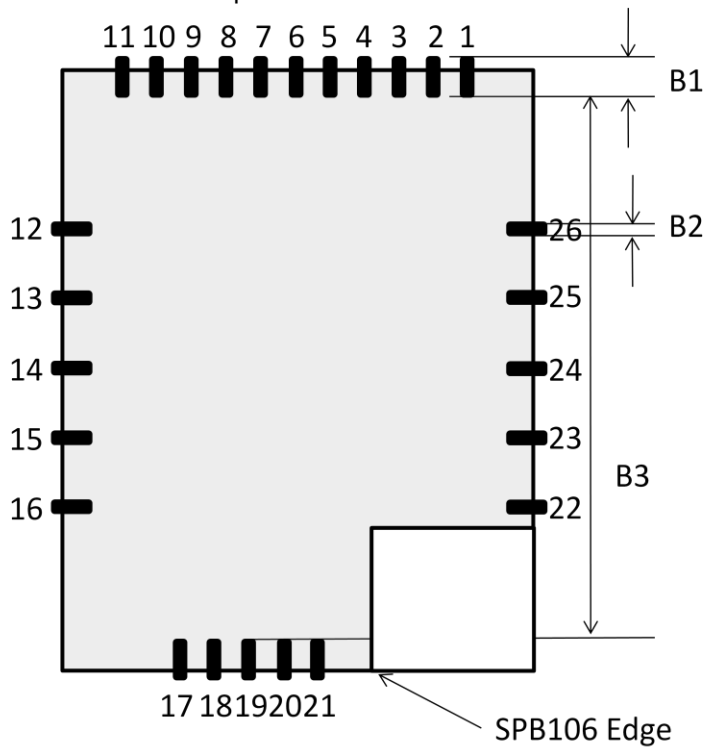


Symbol	Text	Meas [mm]
L	Module Length	25.80
W	Module Width	20.60
P1	Pad length	1.2
P2	Pad width	0.6
A1	Pad edge to PCB edge	0.40
A2	Pad edge to pad edge	22.6
A3	Pad edgeto pad edge min	0.75

SPB106 pads (from top)

6.4 Mounting information

Recommended land pattern on the PCB



Symbol	Text	Meas [mm]
B1	Pad length	2.0
B2	Pad width	0.6
B3	Pad edge to pad edge	22.2

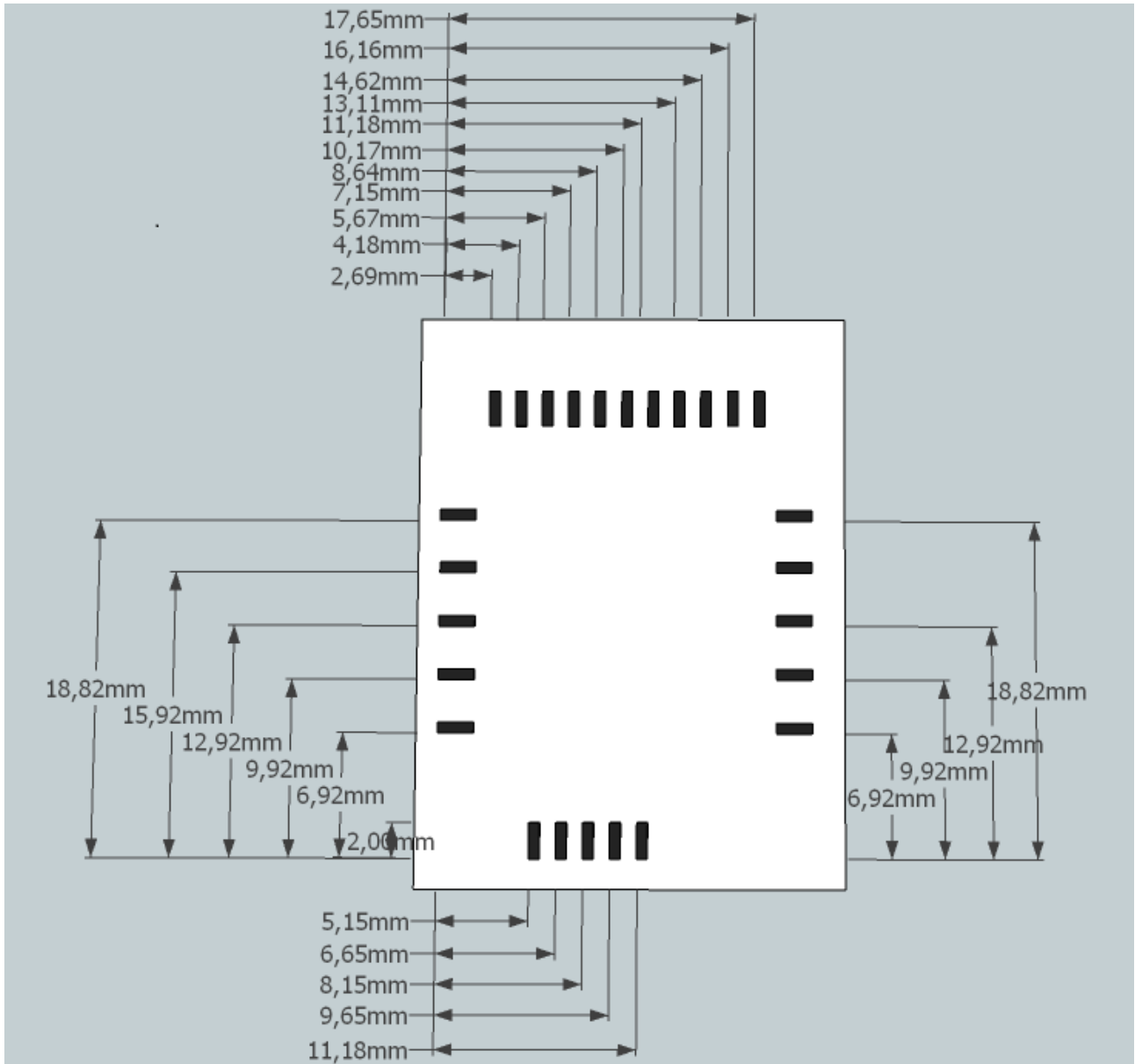


Figure 6-2: Land pattern for SPB106

Figure 6-2 shows the recommended land pattern for the SPB106. All measurements referred to the outside corner of the pad outline.

7 STANDARDS COMPLIANCE

7.1 IEEE/IETF

Standard	Revision	Description
802.11	802.11 R2003	WLAN MAC& PHY
802.11b	802.11 R2003	High rate DSSS (5,5/11Mbit/s)
802.11d	802.11 R2003	Operation in different regulatory domains
802.11e	D9,0 Aug. 2004	QoS enhancements
802.11g	-2003	Extended rate PHY (ERP-PBCC, DSS-OFDM)
802.11i	-2004	Security enhancements
802.11k	Draft 11.0, 2008	Wireless network management
802.11r	Draft 9.0, 2008	Fast BSS transition
802.11h	1997 edition	Bridge tunneling
RFC1023	Inherent	Frame encapsulation
802.15.2		Bluetooth coexistence

Table 7-1: Applicable IEEE standards

7.2 WiFi

Specification	Description	Revision
Wi-Fi 802.11b with WPA system inter operability test plan for IEEE 802.11b devices	802.11b devices with WPA	2.1
WiFi 802.11g with WPA system inter operability test plan	802.11g devices with WPA	2.0
UMA (FMCA)	Convergence services over WiFi-GAN	Aug. 2005
WMM (including WMM Power Save)		Ver 1.1

Table 7-2: Applicable WiFi standards

7.3 Regulatory

Country	Approval authority	Regulatory	Frequency band
USA	FCC	FCC ID X02HDG104	2.4 GHz -2.4835 GHz
Canada	IC	RSS	2.4 GHz -2.4835 GHz
Europe	National	ETSI	2.4 GHz -2.4835 GHz

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Table 7-3: Regulatory Standards

7.3.1 FCC (United States of America)

This equipment complies with Part 15 of the FCC rules and regulations.

To fulfill FCC Certification requirements, an OEM manufacturer must comply with the following regulations:

1. The modular transmitter must be labeled with its own FCC ID number, and, if the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following:

Example of label required for OEM product containing SPB106 module

Contains FCC ID: XO2HDG104

The enclosed device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (i) this device may not cause harmful interference and (ii) this device must accept any interference received, including interference that may cause undesired operation.

Any similar wording that expresses the same meaning may be used.

2. To be used with the SPB106 module, the external antennas have been tested and approved which are specified in here below. The SPB106 Module may be integrated with custom design antennas which OEM installer must authorize following the FCC 15.21 requirements.

WARNING: The Original Equipment Manufacturer (OEM) must ensure that the OEM modular transmitter must be labeled with its own FCC ID number. This includes a clearly visible label on the outside of the final product enclosure that displays the contents shown below. If the FCC ID is not visible when the equipment is installed inside another device, then the outside of the device into which the equipment is installed must also display a label referring to the enclosed equipment.

IMPORTANT: This equipment complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation (FCC 15.19).

The internal / external antenna(s) used for this mobile transmitter must provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter.

Installers must be provided with antenna installation instructions and transmitter operating conditions for satisfying RF exposure compliance. This device is approved as a mobile device with respect to RF exposure compliance, and may only be marketed to OEM installers. Use in portable exposure conditions (FCC 2.1093) requires separate equipment authorization.

IMPORTANT: Modifications not expressly approved by this company could void the user's authority to operate this equipment (FCC section 15.21).

IMPORTANT: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy

and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense (FCC section 15.105).

7.3.2 IC (Canada)

Equipment is subject to certification under the applicable RSSs, shall be permanently labeled on each item, or as an inseparable combination. The label must contain the following information for full compliance:

Certification Number:	IC: 8713A-HDG104
Manufacturer's Name, Trade Name or Brand Name	H&D Wireless AB
Model Name:	HDG104

IMPORTANT: This equipment for which a certificate has been issued is not considered certified if it is not properly labeled. The information on the Canadian label can be combined with the manufacturer's other labeling requirements

IMPORTANT: Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

IMPORTANT: To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that permitted for successful communication.

IMPORTANT: The installer of this radio equipment must ensure that the antenna is located or pointed such that it does not emit RF field in excess of Health Canada limits for the general population. Consult Safety Code 6, obtainable from Health Canada's website www.hc-sc.gc.ca/rpb.

7.3.3 ETSI (Europe)

The SPB106 module has been certified for use in European union countries according to ETSI EN 300 328 (Electromagnetic compatibility and Radio spectrum matters for equipment operating in the 2,4 GHz ISM band using spread spectrum modulation techniques). This standard is harmonized within the European Union and covering essential requirements under article 3.2 of the R&TTE-directive.

If the SPB106 module are incorporated into a product, the manufacturer must ensure compliance of the final end-user product to the European harmonized EMC and low voltage/safety standards. A declaration of conformity must be issued for the product including compliance references to these standards. Underlying the declaration of conformity a technical construction file (TCF), including all relevant test reports and technical documentation, must be issued and kept on file as described in Annex II of the R&TTE-directive.

Furthermore, the manufacturer must maintain a copy of the SPB106 module documentation and ensure the final product does not exceed the specified power ratings, antenna specifications, and/or installation requirements as specified in the user manual. If any of these specifications are exceeded in the final product, a complete re-test must be made in order to comply with all relevant standards as basis for CE-marking. A submission to notified body must be used only if deviations from standards have been found or if non-harmonized standards have been used.

8 SALES OFFICES

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